

REMARKS

Claims 1-5 are pending in the present application. As will be discussed below, Claims 2 and 3 have been amended. No new matter has been added. Accordingly, entry of the present Amendment is requested.

Claims 2 and 3 stand rejected under 35 U.S.C. § 112, second paragraph, as allegedly being indefinite. In particular, it is asserted that Claim 2 is unclear as to whether the tape carrier is in addition to the lead frame or in place of the lead frame. It is also asserted that Claim 3 is unclear as to whether Applicant is only claiming an adhesive tape capable of being adhered to a lead frame or is actually claiming the lead frame and tape together.

In response, Applicants have amended Claim 2 to rewrite it in independent form. Additionally, the preamble to Claim 3 has been amended to recite "a pressure-sensitive adhesive tape."

In view of the foregoing, Applicants respectfully submit that Claims 2 and 3 now more clearly comply with the requirements of 35 U.S.C. § 112, second paragraph. Accordingly, withdrawal of this rejection is requested.

Claim 3 stands rejected under 35 U.S.C. § 102(b) as allegedly being anticipated by U.S. Patent No. 5,277,972 to Sakumoto *et al.* Additionally, Claims 1 and 3-5 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 5,977,615 to Yamaguchi *et al.* in view of Sakumoto. Lastly, Claim 2 stands rejected under 35 U.S.C. § 103(a) as being unpatentable over Yamaguchi and Sakumoto, and further in view of WO 98/35283 to Oida *et al.*

Applicants respectfully traverse these rejections for the following reasons.

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The present invention and the cited references are different with regard to the use of the tape. The tapes of both Sakumoto *et al.* and Yamaguchi *et al.* are for fixing the lead frames. In contrast, the tape of the present invention is for masking at the resin encapsulating. The pressure-sensitive adhesive tape of the present claimed invention is released cleanly without leaving any trace. As discussed in the paragraph bridging pages 7 and 8 of the Amendment filed October 7, 2002, as demonstrated in Comparative Example 2 of the present application, poor results are obtained when a tape having a thermal shrinkage above 3 % is used. The evidence of record refutes any suggestion that the cited references taught or suggested the method of the present claimed invention.

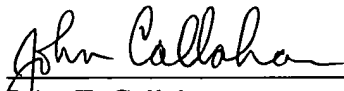
In view of the foregoing, Applicants respectfully submit that the present claimed invention is not anticipated or rendered *prima facie* obvious by the cited references. Accordingly, withdrawal of the rejections is requested.

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

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The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,


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PATENT TRADEMARK OFFICE

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APPENDIX
VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

The claims are amended as follows:

2. (Amended) A resin encapsulating method for a semiconductor chip [according to claim 1, wherein a tapecarrier film is used in place of the leadframe] comprising adhering a pressure-sensitive adhesive tape to a tape carrier film, bonding a semiconductor chip to the tape carrier film having the pressure-sensitive adhesive tape adhered thereto, encapsulating the semiconductor chip with a resin and a mold, and stripping the pressure-sensitive adhesive tape, wherein the pressure-sensitive adhesive tape has a thermal shrinkage of 3% or less on resin encapsulating.

3. (Twice Amended) A pressure-sensitive adhesive tape, [to be adhered to a leadframe,] which can be used in the resin encapsulating method for a semiconductor chip according to claim 1 or 2 and has a thermal shrinkage of 3% or less on resin encapsulating and a pressure-sensitive adhesive strength of 400 gf/20 mm or less at 23°C [on resin encapsulating] after the adhesive tape being heated at 180°C.